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SHEET 1 OF 1

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 005199 USA/Consilium/Consilium		SERIAL NO. 09/725,908 <div style="text-align: center; font-weight: bold; font-size: 1.2em;">RECEIVED</div> <div style="text-align: center;">OCT 10 2003</div>	
				APPLICANT Yueshian T. CHI et al.		Technology Center 2100	
				FILING DATE November 30, 2000		GROUP 2152	

U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
✓	5,901,313	05/04/99	Wolf et al.			09/02/97
✓	6,002,989	12/14/99	Shiba et al.			04/01/97
✓	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
✓	6,340,602	01/22/02	Johnson et al.			02/12/01
✓	6,345,288	02/05/02	Reed et al.			05/15/00
✓	6,368,879	04/09/02	Toprac			09/22/99
✓	US-2002/0107604	08/08/02	Riley et al.			12/06/00
✓	6,470,230	10/22/02	Toprac et al.			01/04/00
✓	6,482,660	11/19/02	Conchieri et al.			03/19/01
✓	6,567,717	05/20/03	Krivokapic et al.			01/19/00

FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
✓	WO 99/59200	11/18/99	WIPO			X	
✓	WO 01/52319	07/19/01	WIPO			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)	
✓	Williams, Randy, Dadi Gudmundsson, Kevin Monahan, Raman Nurani, Meryl Stoller and J. George Shanthikumar. October 1999. "Optimized Sample Planning for Wafer Defect Inspection," <i>Semiconductor Manufacturing Conference Proceedings, 1999 IEEE International Symposium on Santa Clara, CA</i> . Piscataway, NJ. pp. 43 - 46.
✓	23 July 2003. Invitation to Pay Additional Fees and Communication Relating to the Results of the Partial International Search for PCT/US02/19116.
✓	01 August 2003. Written Opinion for PCT/US01/27406.
✓	20 August 2003. Written Opinion for PCT/US01/22833.

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~	3,205,485	09/07/65	Noltingk			10/21/60
~	3,229,198	01/11/66	Libby			09/28/62
~	4,000,458	12/28/76	Miller et al.			08/21/75
~	4,302,721	11/24/81	Urbanek et al.			05/15/79
~	4,750,141	06/07/88	Judell et al.			11/26/85
~	4,757,259	07/12/88	Charpentier			11/05/86
~	4,938,600	07/03/90	Into			02/09/89
~	5,283,141	02/01/94	Yoon et al.			03/05/92
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~	5,497,381	03/05/96	O'Donoghue et al.			06/01/95
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~	5,519,605	05/21/96	Cawfield			10/24/94
~	5,526,293	06/11/96	Mozumder et al.			12/17/93
~	5,541,510	06/30/96	Danielson			04/06/95
~	5,546,312	08/13/96	Mozumder et al.			02/24/94
~	5,553,195	09/03/96	Meijer			09/29/94
~	5,602,492	02/11/97	Cresswell et al.			04/28/94
~	5,617,023	04/01/97	Skalski			02/02/95
~	5,627,083	05/06/97	Tounai			05/12/95
~	5,642,296	06/24/97	Saxena			07/29/93
~	5,646,870	07/08/97	Krivokapic et al.			02/13/95
~	5,649,169	07/15/97	Berezin et al.			06/20/95
~	5,654,903	08/05/97	Reitman et al.			11/07/95
~	5,663,797	09/02/97	Sandhu			05/16/96
~	5,665,199	09/09/97	Sahota et al.			06/23/95
~	5,666,297	09/09/97	Britt et al.			05/13/94

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✓	5,667,424	09/16/97	Pan			09/25/96
✓	5,674,787	10/07/97	Zhao et al.			01/16/96
✓	5,719,796	02/17/98	Chen			12/04/95
✓	5,735,055	04/07/98	Hochbein et al.			04/23/96
✓	5,761,064	06/02/98	La et al.			10/06/95
✓	5,777,901	07/07/98	Berezin et al.			09/29/95
✓	5,787,021	07/28/98	Samaha			12/18/95
✓	5,787,269	07/28/98	Hyodo			09/19/95
✓	5,825,913	10/20/98	Rostami et al.			07/18/95
✓	5,857,258	01/12/99	Penzes et al.			05/12/94
✓	5,910,846	06/08/99	Sandhu			08/19/97
✓	5,943,237	08/24/99	Van Boxem			10/17/97
✓	5,960,185	09/28/99	Nguyen			06/24/96
✓	5,961,369	10/05/99	Bartels et al.			06/04/98
✓	5,978,751	11/02/99	Pence et al.			02/25/97
✓	6,017,771	01/25/00	Yang et al.			04/27/98
✓	6,036,349	03/14/00	Gombar			07/26/96
✓	6,064,759	05/16/00	Buckley et al.			11/06/97
✓	6,072,313	06/06/00	Li et al.			06/17/97
✓	6,097,887	08/01/00	Hardikar et al.			10/27/97
✓	6,108,092	08/22/00	Sandhu			06/08/99
✓	6,127,263	10/03/00	Parikh			07/10/98
✓	6,136,163	10/24/00	Cheung et al.			03/05/99
✓	6,141,660	10/31/00	Bach et al.			07/16/98
✓	6,143,646	11/07/00	Wetzel			06/03/97
✓	6,148,099	11/14/00	Lee et al.			07/03/97
✓	6,148,239	11/14/00	Funk et al.			12/12/97

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/	6,169,931	01/02/01	Runnels			06/29/98
/	6,172,756	01/09/01	Chalmers et al.			12/11/98
/	6,173,240	01/09/01	Sepulveda et al.			11/02/98
/	6,191,864	02/20/01	Sandhu			02/29/00
/	6,204,165	03/20/01	Ghoshal			06/24/99
/	6,210,983	04/03/01	Atchison et al.			06/15/99
/	6,214,734	04/10/01	Bothra et al.			11/20/98
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/	6,276,989	08/21/01	Campbell et al.			08/11/99
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—	2001/0042690	11/22/01	Talieh			12/14/00
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—	6,334,807	01/01/02	Lebel et al.			04/30/99
✓	6,336,841	01/08/02	Chang			03/29/01
—	2002/0032499	03/14/02	Wilson et al.			05/04/01
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—	6,368,883	04/09/02	Bode et al.			08/10/99
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—	6,379,980	04/30/02	Toprac			07/26/00
—	6,388,253	05/14/02	Su			11/02/00
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—	6,397,114	05/28/02	Eryurek et al.			05/03/99
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—	2002/0070126	06/13/02	Sato et al.			09/19/01
—	2002/0081951	06/27/02	Boyd et al.			02/20/02
—	2002/0089676	07/11/02	Pecen et al.			04/26/00
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—	6,455,937	09/24/02	Cunningham			03/17/99

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/	2002/0149359	10/17/02	Crouzen et al.			08/18/01
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/	2002/0185658	12/12/02	Inoue et al.			06/14/01
/	2002/0193902	12/19/02	Shanmugasundram et al.			06/18/02
/	2002/0197745	12/26/02	Shanmugasundram et al.			08/31/01
/	2002/0197934	12/26/02	Paik			11/30/01
/	2002/0199082	12/26/02	Shanmugasundram et al.			06/18/02
/	6,503,839	01/07/03	Gonzales et al.			07/03/01
/	2003/0020909	01/30/03	Adams et al.			04/09/01
/	2003/0020928	01/30/03	Ritzdorf et al.			07/09/01
/	6,517,413	02/11/03	Hu et al.			10/25/00

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
/	61-66104	04/04/86	Japan			X	
/	3-202710	09/04/91	Japan			X	
/	8-23166	01/23/96	Japan			X	
/	9-246547	09/19/97	Japan			X	
/	WO 98/05066	02/05/98	WIPO			X	
/	10-34522	02/10/98	Japan			X	
/	0 869 652	10/07/98	Europe			X	
/	WO 99/09371	02/25/99	WIPO			X	
/	0 910 123	04/21/99	Europe			X	
/	0 932 194	07/28/99	Europe			X	
/	WO 00/00874	01/06/00	WIPO			X	
/	2000-183001	06/30/00	Japan			X	

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						Yes	No
/	1 071 128	01/24/01	Europe			X	
/	WO 01/18623	03/15/01	WIPO			X	
/	WO 01/25865	04/12/01	WIPO			X	
/	434103	05/16/01	Taiwan			X	
/	436383	05/28/01	Taiwan			X	
/	455938	09/21/01	Taiwan			X	
/	455976	09/21/01	Taiwan			X	
/	2001-284299	10/12/01	Japan			X	
/	2001-305108	10/31/01	Japan			X	
/	2002-9030	01/11/02	Japan			X	
/	WO 02/074491	09/26/02	WIPO			X	
/	2002-343754	11/29/02	Japan			X	

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/	Ostani, Yu. Ya. October 1981. "Optimization of Thickness Inspection of Electrically Conductive Single-Layer Coatings with Laid-on Eddy-Current Transducers (Abstract)." <i>Defektoskopiya</i> , vol. 17, no. 10, pp. 45-52. Moscow, USSR.
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/	Herrmann, D. 1988. "Temperature Errors and Ways of Elimination for Contactless Measurement of Shaft Vibrations (Abstract)." <i>Technisches Messen</i> TM , vol. 55, no. 1, pp. 27-30. West Germany.
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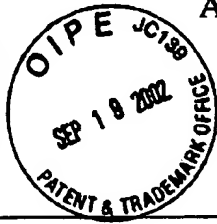
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Yueshian T. CHI et al.

FILING DATE
November 30, 2000

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
—	6,175,777	01/16/01	Kim			01/16/98
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—	6,185,324	02/06/01	Ishihara et al.			01/31/95
—	6,192,291	02/20/01	Kwon			10/08/98
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—	6,236,903	05/22/01	Kim et al.			09/25/98
—	6,240,330	05/29/01	Kurtzberg et al.			05/28/97

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
—	11-135601	05/21/99	Japan				X
—	WO 00/05759	02/03/00	WO			X	
—	WO 00/35063	06/15/00	WO			X	

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—	July 5, 2001. "Motorola and Advanced Micro Devices Buy ObjectSpace Catalyst Advanced Process Control Product for Five Wafer Fabs." Semiconductor FABTECH. www.semiconductorfabtech.com/industry.news/9907/20.07.shtml
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—	Sonderman, Thomas. 2002. "APC as a Competitive Manufacturing Technology: AMD's Vision for 300mm." AEC/APC.

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9/21/01

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**INFORMATION DISCLOSURE
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ATTY. DOCKET NO.
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—	6,240,331	05/29/01	Yun			08/18/98
—	6,248,602	06/19/01	Bode et al.			11/01/99
—	6,252,412	06/26/01	Talbot et al.			01/08/99
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—	6,292,708	09/18/01	Allen et al.			06/11/98
—	6,298,274	10/02/01	Inoue			09/01/99
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—	6,345,315	02/05/02	Mishra			08/12/98
—	6,366,934	04/02/02	Cheng et al.			06/02/99

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
—	WO 00/79355 A1	12/28/00	WO			X	
—	2001-76982	03/23/01	Japan				X
—	WO 01/33501 A1	05/10/01	WO			X	

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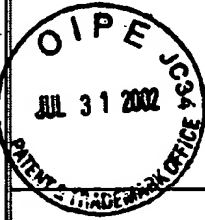
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—	5,220,517	06/15/93	Sierk et al.			08/31/90
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						Yes	No
—	2,050,247	08/29/91	Canada			X	
—	2,165,847	08/29/91	Canada			X	
—	2,194,855	08/29/91	Canada			X	
—	05-151231	06/18/93	Japan				X
—	05-216896	08/27/93	Japan				X
—	05-266029	10/15/93	Japan				X
—	06-110894	04/22/94	Japan				X
—	06-176994	06/24/94	Japan				X
—	06-252236	09/09/94	Japan				X
—	06-260380	09/16/94	Japan				X
—	1072967A3	11/21/01	Europe			X	

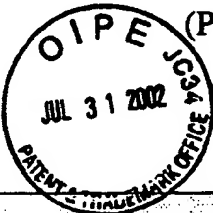

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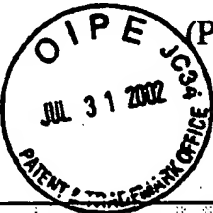

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						Yes	No
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
—	Zhou, Zhen-Hong and Rafael Reif. August 1995. "Epi-Film Thickness Measurements Using Emission Fourier Transform Infrared Spectroscopy—Part II: Real-Time <i>in Situ</i> Process Monitoring and Control." IEEE Transactions on Semiconductor Manufacturing, Vol. 8, No. 3.						
—	Telfeyan, Roland, James Moyne, Nauman Chaudhry, James Pugmire, Scott Shellman, Duane Boning, William Moyne, Arnon Hurwitz, and John Taylor. October 1995. "A Multi-Level Approach to the Control of a Chemical-Mechanical Planarization Process." Minneapolis, Minnesota: 42 nd National Symposium of the American Vacuum Society.						
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						Yes	No
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—	Boning, Duane, William Moyne, Taber Smith, James Moyne, Roland Telfeyan, Arnon Hurwitz, Scott Shellman, and John Taylor. October 1996. "Run by Run Control of Chemical-Mechanical Polishing." <i>IEEE Trans. CPMT (C)</i> , Vol. 19, No. 4, pp. 307-314.						
—	Edgar, Thomas F., Stephanie W. Butler, Jarrett Campbell, Carlos Pfeiffer, Chris Bode, Sung Bo Hwang, and K.S. Balakrishnan. May 1998. "Automatic Control in Microelectronics Manufacturing: Practices, Challenges, and Possibilities." <i>Automatica</i> , Vol. 36, pp. 1567-1603, 2000.						
—	Chemali, Chadi El, James Moyne, Kareemullah Khan, Rock Nadeau, Paul Smith, John Colt, Jonathan Chapple-Sokol, and Tarun Parikh. November 1998. "Multizone Uniformity Control of a CMP Process Utilizing a Pre and Post-Measurement Strategy." Seattle, Washington: SEMETECH Symposium.						
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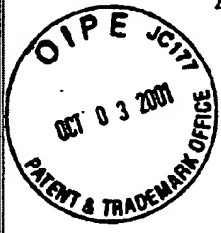
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—	5,108,570	04/28/92	Wang			03/30/90
—	5,236,868	08/17/93	Nulman			04/20/90
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—	5,309,221	05/03/94	Fischer et al.			12/31/91
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—	5,398,336	03/14/95	Tantry et al.			06/16/93
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—	5,629,216	05/13/97	Wijaranakula et al.			02/27/96

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						Yes	No
—	HEI 1-283934	11/15/89	Japan			X	
—	HEI 8-149583	06/07/96	Japan			X	
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—	EP 0877308	11/11/98	Europe			X	
—	HEI 11-67853	03/09/99	Japan			X	

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—	Runyan, W. R., and K. E. Bean. 1990. "Semiconductor Integrated Circuit Processing Technology." pg. 48. Reading, Massachusetts: Addison-Wesley Publishing Company.

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				FILING DATE November 30, 2000		GROUP 2152	

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/	Zorich, Robert. 1991. <i>Handbook of Quality Integrated Circuit Manufacturing</i> . pp. 464-498 San Diego, California: Academic Press, Inc.
/	Rampalli, Prasad, Arakere Ramesh, and Nimish Shah. 1991. CEPT—A Computer-Aided Manufacturing Application for Managing Equipment Reliability and Availability in the Semiconductor Industry. New York, New York: IEEE.
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EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS	
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—	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
—	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
/	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
/	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
FOREIGN PATENT DOCUMENTS							
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						Yes	No
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
/	Dishon, G., M. Finarov, R. Kipper, J.W. Curry, T. Schraub, D. Trojan, 4 th Stambaugh, Y. Li and J. Ben-Jacob. February 1996. "On-Line Integrated Metrology for CMP Processing." Santa Clara, California: VMIC Speciality Conferences, 1 st International CMP Planarization Conference.						
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS
/	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service		

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	Translation	
						Yes	No

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/	SEMI. July 1998. <i>New Standard: Provisional Specification for CIM Framework Domain Architecture</i> . Mountain View, California: SEMI Standards. SEMI Draft Doc. 2817.
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